1. Record Nr. UNINA9910456280903321

Autore	Bantjes Rod
Titolo	Improved earth : prairie space as modern artefact, 1869-1944 / / Rod Bantjes
Pubbl/distr/stampa	Toronto, [Ontario] ; ; Buffalo, [New York] ; ; London, [England] : , : University of Toronto Press, , 2005 ©2005
ISBN	1-281-99452-9 9786611994525 1-4426-7603-5
Descrizione fisica	1 online resource (217 p.)
Disciplina	307.72097124
Soggetti	Landscapes - Social aspects - Saskatchewan Rural development - Saskatchewan Land settlement - Social aspects - Saskatchewan Sociology, Rural - Saskatchewan Rural development - Sociological aspects - Saskatchewan Electronic books. Saskatchewan Politics and government Saskatchewan Rural conditions
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Bibliographic Level Mode of Issuance: Monograph
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Frontmatter -- Contents -- Illustrations -- Chapter 1. Introduction -- Chapter 2. Groundwork: The Dominion Survey -- Chapter 3. Modernity in the Countryside: Contested Rural Space -- Chapter 4. Local Governance as Spatial Practice: State Formation -- Chapter 5. Utopics of Resistance: Agrarian Class Formation -- Chapter 6. Conclusion: The Trans-local and Resistance -- Notes -- Bibliography -- Index
Sommario/riassunto	Improved Earth is a history of the making of ?abstract spaces of modernity? in the setting of the Canadian prairies, particularly rural Saskatchewan, from 1869 to 1944. Rod Bantjes demonstrates how three interrelated projects ? state formation, agrarian class formation, and the transformation of the environment ? were conceived in spatial

	terms and employed competing visions of spatial possibility.Bantjes proposes that the prairies be thought of as a site of modernity, and makes a case for viewing prairie farmers as ?modernists? who not only embraced, but took an active role in the making of modernity. Indeed, many of the questions that excited the imaginations of prairie politicians and reformers are alive today: the ecological and social value of ?localization? in agricultural production; the potentials for ? community? maintained and linked by transportation and communications technologies; and the possibilities of democratic decentralization within large translocal networks.The first systematic treatment of the spatial dimensions of the colonization of the prairie west, Improved Earth is a unique and thorough study certain to provoke new debates about the way space and time are imagined.

2. Record Nr. UNINA9911019683103321

Titolo	Structural dynamics of electronic and photonic systems / / edited by Ephraim Suhir, David S. Steinberg, T.X. Yu
Pubbl/distr/stampa	Hoboken, N.J., : Wiley, 2010
ISBN	9786613072368 9781283072366 128307236X 9780470886656 047088665X 9780470886793 047088679X 9780470950012 0470950013 9780470886786 0470886781
Descrizione fisica	1 online resource (610 p.)
Altri autori (Persone)	SuhirEphraim YuT. X <1941-> (Tongxi) SteinbergDavid S
Disciplina	621.382
Soggetti	Electronic apparatus and appliances - Reliability Optoelectronic devices - Reliability Fault tolerance (Engineering) Microstructure Structural dynamics

Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Includes index.
Nota di contenuto	Structural Dynamics of Electronic and Photonic Systems; Contents; Preface; Contributors; 1 Some Major Structural Dynamics-Related Failure Modes and Mechanisms in Micro- and Opto-Electronic Systems and Dynamic Stability of These Systems; 2 Linear Response to Shocks and Vibrations; 3 Linear and Nonlinear Vibrations Caused by Periodic Impulses; 4 Random Vibrations of Structural Elements in Electronic and Photonic Systems; 5 Natural Frequencies and Failure Mechanisms of Electronic and Photonic Structures Subjected to Sinusoidal or Random Vibrations 6 Drop/Impact of Typical Portable Electronic Devices: Experimentation and Modeling7 Shock Test Methods and Test Standards for Portable Electronic Devices; 8 Dynamic Response of Solder Joint Interconnections to Vibration and Shock; 9 Test Equipment, Test Methods, Test Fixtures, and Test Sensors for Evaluating Electronic Equipment; 10 Correlation between Package-Level High-Speed Solder Ball Shear/Pull and Board-Level Mechanical Drop Tests with Brittle Fracture Failure Mode, Strength, and Energy 11 Dynamic Mechanical Properties and Microstructural Studies of Lead-Free Solders in Electronic Packaging12 Fatigue Damage Evaluation for Microelectronic Components Subjected to Vibration; 13 Vibration Considerations for Sensitive Research and Production Facilities; 14 Applications of Finite Element Analysis: Attributes and Challenges; 15 Shock Simulation of Drop Test of Hard Disk Drives; 16 Shock Protection of Portable Electronic Devices Using a "Cushion" of an Array of Wires (AOW); 17 Board-Level Reliability of Lead-Free Solder under Mechanical Shock and Vibration Loads 18 Dynamic Response of PCB Structures to Shock Loading in Reliability Tests19 Linear Response of Single-Degree-of-Freedom System to Impact Load: Could Shock Tests Adequately Mimic Drop Test Conditions?; 20 Shock Isolation of Micromachined Device for High-g Applications; 21 Reliability Assessment of Microelectronics Packages Using Dynamic Testing Methods; 22 Thermal Cycle and Vibration/Drop Reliability of Area Array Package Assemblies; 23 Could an Impact Load of Finite Duration Be Substituted with an Instantaneous Impulse?; Index
Sommario/riassunto	"The proposed book will offer comprehensive and versatile methodologies and recommendations on how to determine dynamic characteristics of typical micro- and opto-electronic structural elements (printed circuit boards, solder joints, heavy devices, etc.) and how to design a viable and reliable structure that would be able to withstand high-level dynamic loading. Particular attention will be given to portable devices and systems designed for operation in harsh environments (such as automotive, aerospace, military, etc.) In-depth discussion from a mechanical engineer's viewpoint will be conducted to the key components' level as well as the whole device level. Both theoretical (analytical and computer-aided) and experimental methods of analysis will be addressed. The authors will identify how the failure control parameters (e.g. displacement, strain and stress) of the vulnerable components may be affected by the external vibration or shock loading, as well as by the internal parameters of the infrastructure of the device. Guidelines for material selection, effective protection and test methods will be developed for engineering practice"

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"The proposed book will offer comprehensive and versatile methodologies and recommendations on how to determine dynamic characteristics of typical micro- and opto-electronic structural elements (printed circuit boards, solder joints, heavy devices, etc.) and how to design a viable and reliable structure that would be able to withstand high-level dynamic loading"--